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**Breaking Down  
the Barriers:  
Bringing Disruptive  
Memory Technology  
to Market**



**FLASH FORWARD**



# How Radical Should Changes Be?



## **Disruptive**

**Interrupt the normal course of  
Technology**

## **Evolutionary.**

**Continue to change from a lower  
to a higher, more complex, or  
better state of Technology**

# How Disruptive can Technology be?



- **New Applications, New Infrastructure and New Market**

**OR**

- **Improve the existing applications**
- **More applications without creating a new infrastructure**

# How Disruptive Technology can be effective?

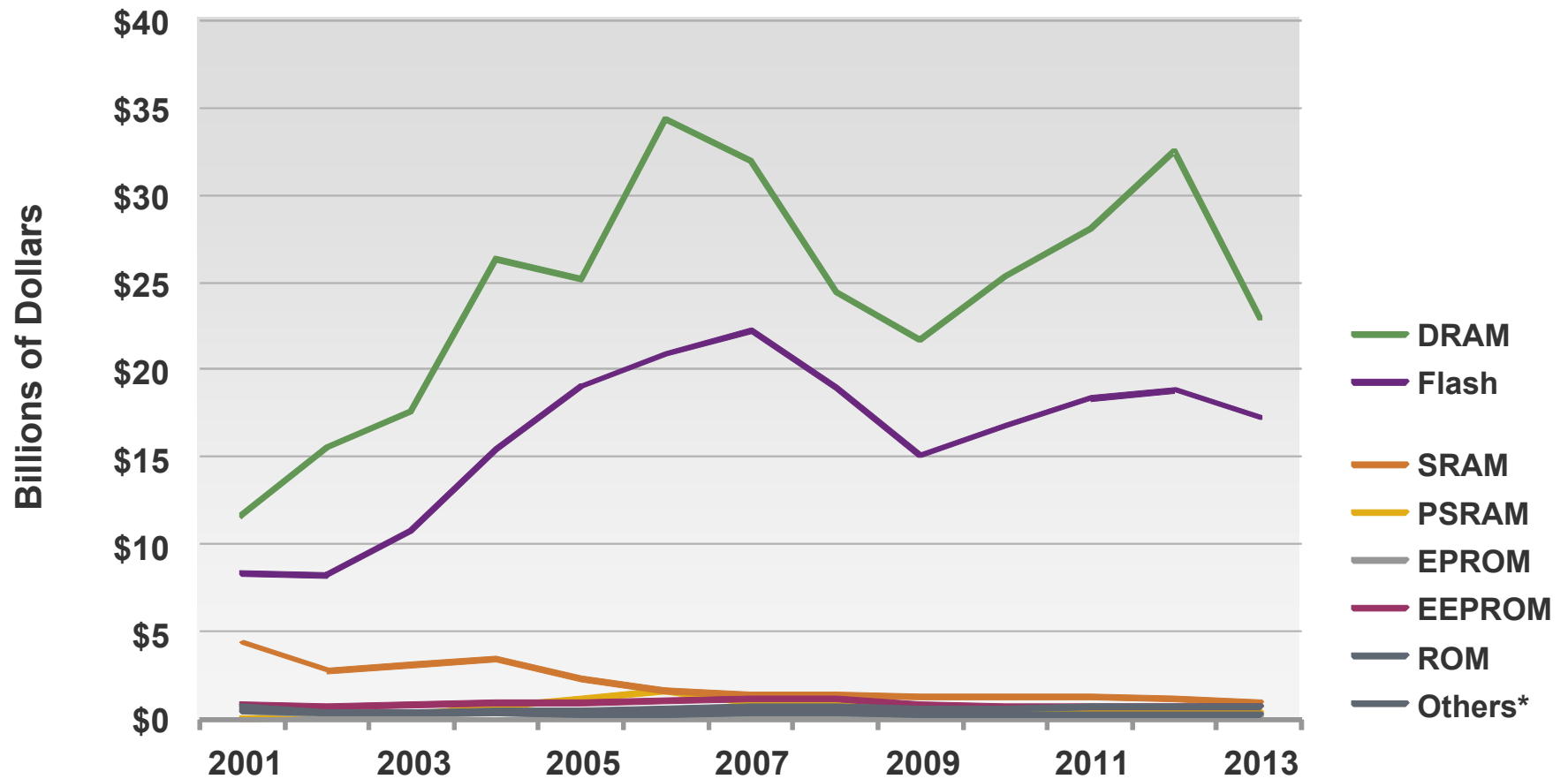


**“In spite of the rare instances when disruptive technology has been successfully deployed in the memory industry, we operate under the assumption that it can and should be, without fully examining how to do it or even if we should.”**

**Spansion as one of the few  
companies that has successfully  
deployed a disruptive technology  
in the memory market.**

# Polarized Mainstream Memory Use

Defines infrastructure and ecosystem



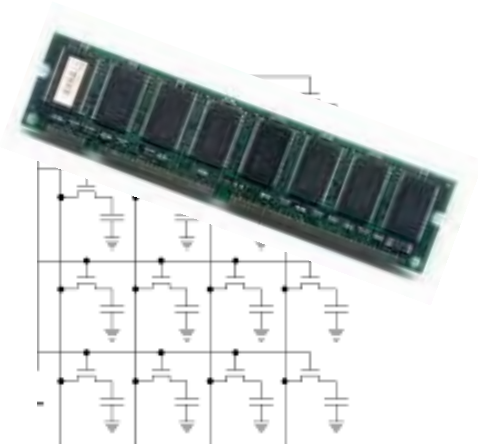
Source: Gartner (February 2009)

\* Excludes memory embedded in ASIC or ASSP components.

# Memory Attributes



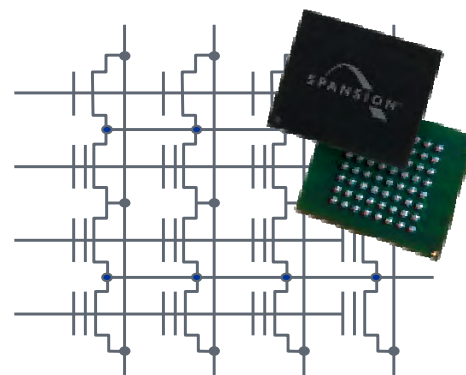
Keep discrete or combine in one technology?



## DRAM

Volatile + Refresh  
Most expensive  
Very fast read & write

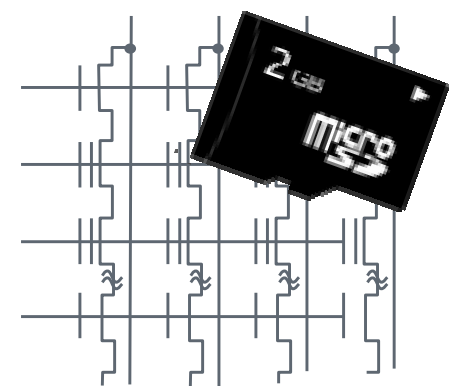
Best for  
Real time code  
execution cache



## NOR

Non-volatile  
Low cost  
Fast read  
High reliability

Best for  
code storage and  
execution



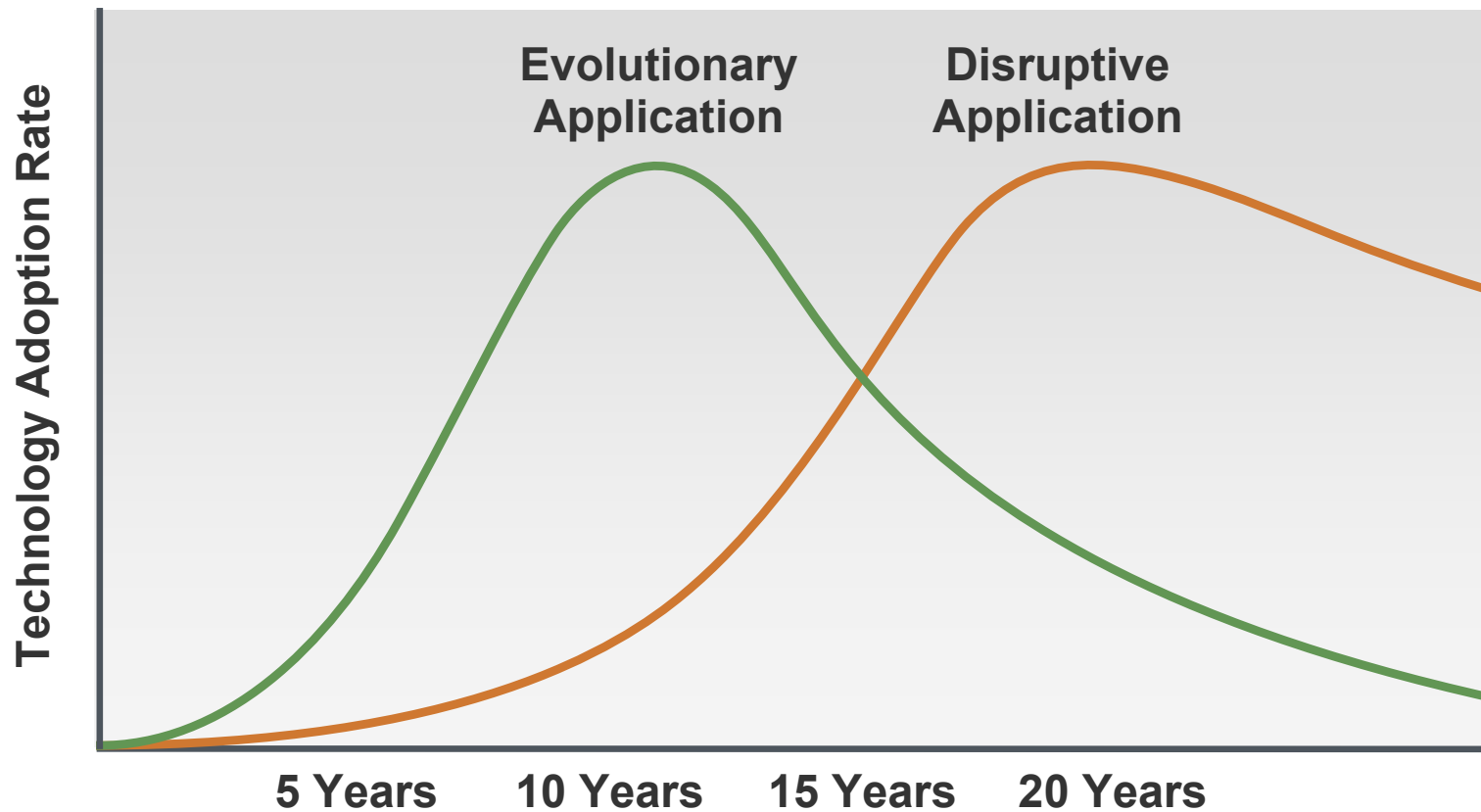
## NAND

Non-volatile  
Lowest cost  
Fast write & erase

Best for  
media  
storage

# Does Disruptive Technology = Disruptive Use?

Sometimes ... but then it takes much longer to ramp



Source: Spansion

# Next-Generation Memory Specification



## Table stakes to deliver “acceptable” system benefits

- **Competitive cost**
- **Compatible with high-volume manufacturing techniques**
- **Architecture balance**
  - **Performance**
    - High speed read
    - High speed program, erase/overwrite
  - **Low power**
- **Reliability**
  - Data retention
  - Endurance

## “Acceptable” defined by the infrastructure

- **What is required from the memory device**
- **What can be exploited by the system software and hardware**



# Technology & Infrastructure Maturity



	Mature	Evolving	Disruptive (Near Term)	Disruptive (Long Term)
Technology	Floating Gate	Charge Trapping (e.g. MirrorBit®)	PCM	Other RCM RRAM MRAM
Mass Market Maturity	20 years	7 years	Years Away	Many Years Away

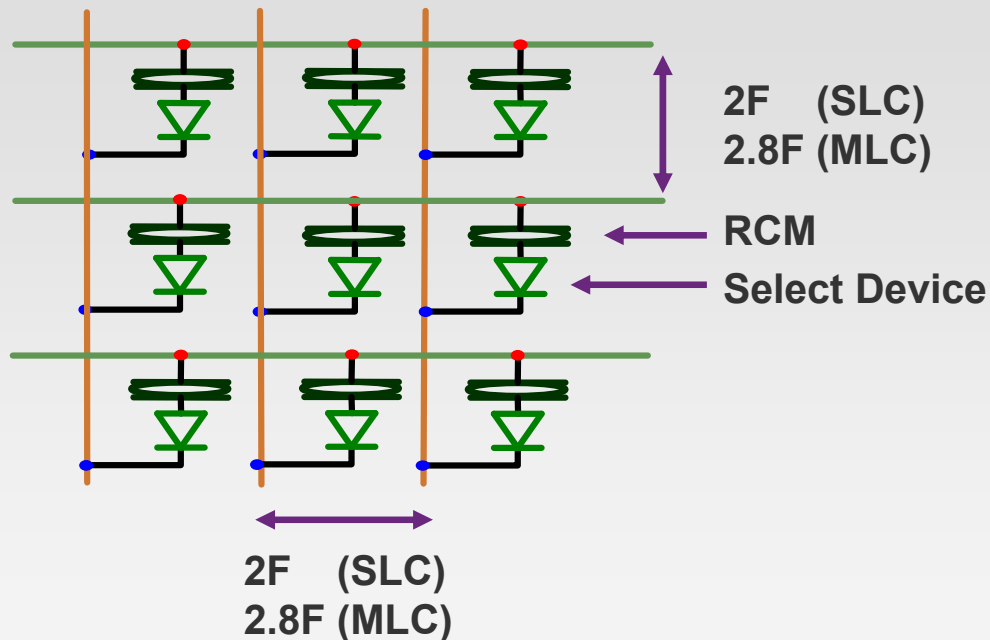
Source: Spansion

# Resistive Change Memory



Near term or long term technology solution?

## The Ideal RCM Technology



1.  $4\text{-}5F^2$  MLC cell
2. Compact select device with sufficient drive current, e.g. vertical diode
3. Minimum pitch, fine-line, high conductivity interconnect in both directions

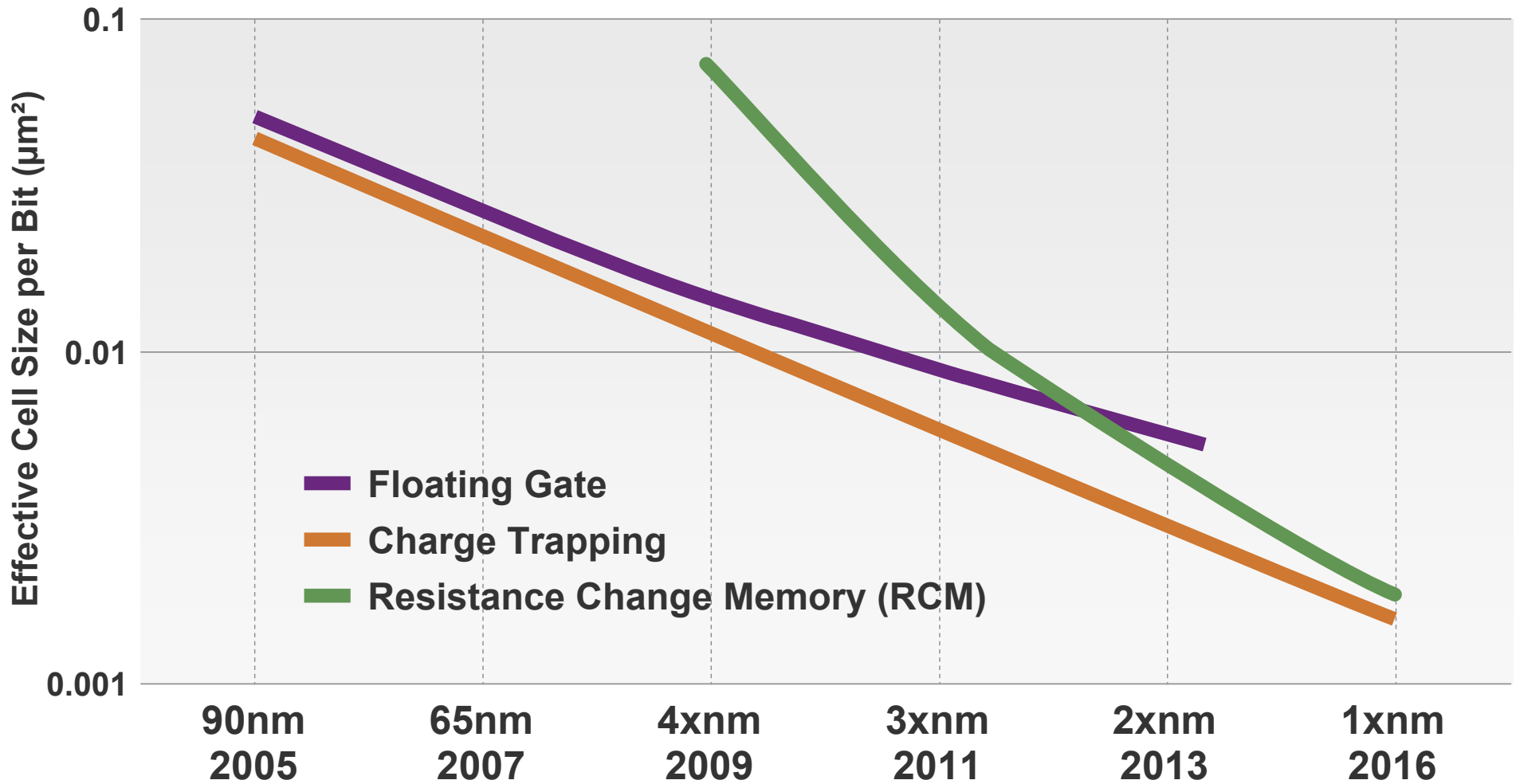
# Near Term: Phase Change Memory

## Challenges the industry has to overcome

	Issue	Risk	Comments
1	<b>Performance:</b> Programming speed	High	High current limits parallelism in programming
2	<b>Manufacturability:</b> Process complexity	High	Challenging integration with significant number of critical masking steps
3	<b>Cost and Manu:</b> Multi-level capability	High	Resistance drift challenges state placement
4	<b>Cost</b> Complexity vs. existing technology	High	SLC significantly more complex process
5	<b>Cost</b> Cell size	High	Compromises for shrink from 12F <sup>2</sup>
6	<b>Cost and Manu.</b> Scalability	High	Select devices may not scale. GST area is already sub-lithographic
7	Bit alterability	Low	Truly disruptive for NVM

# Charge Trapping: Innovation at the Cell – Evolution in the System

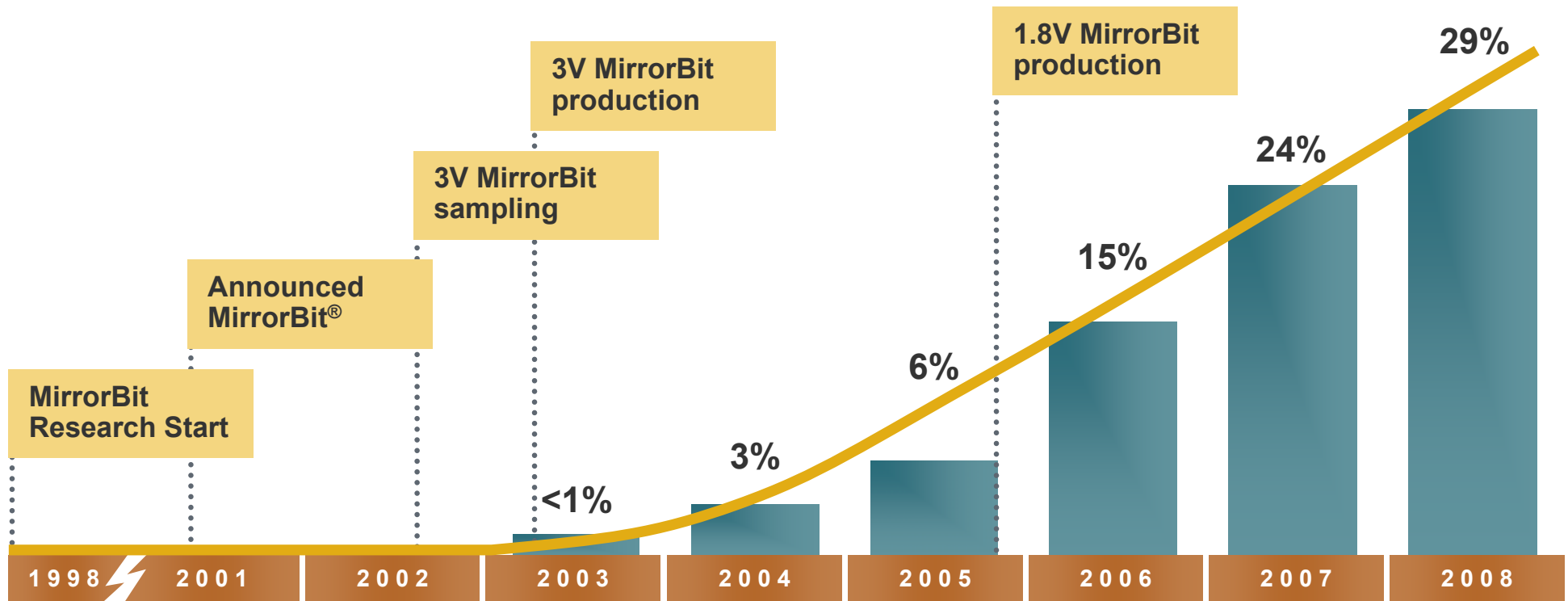
# Disruptive Scalability



Source: Spansion estimates

# Evolutionary Ramp

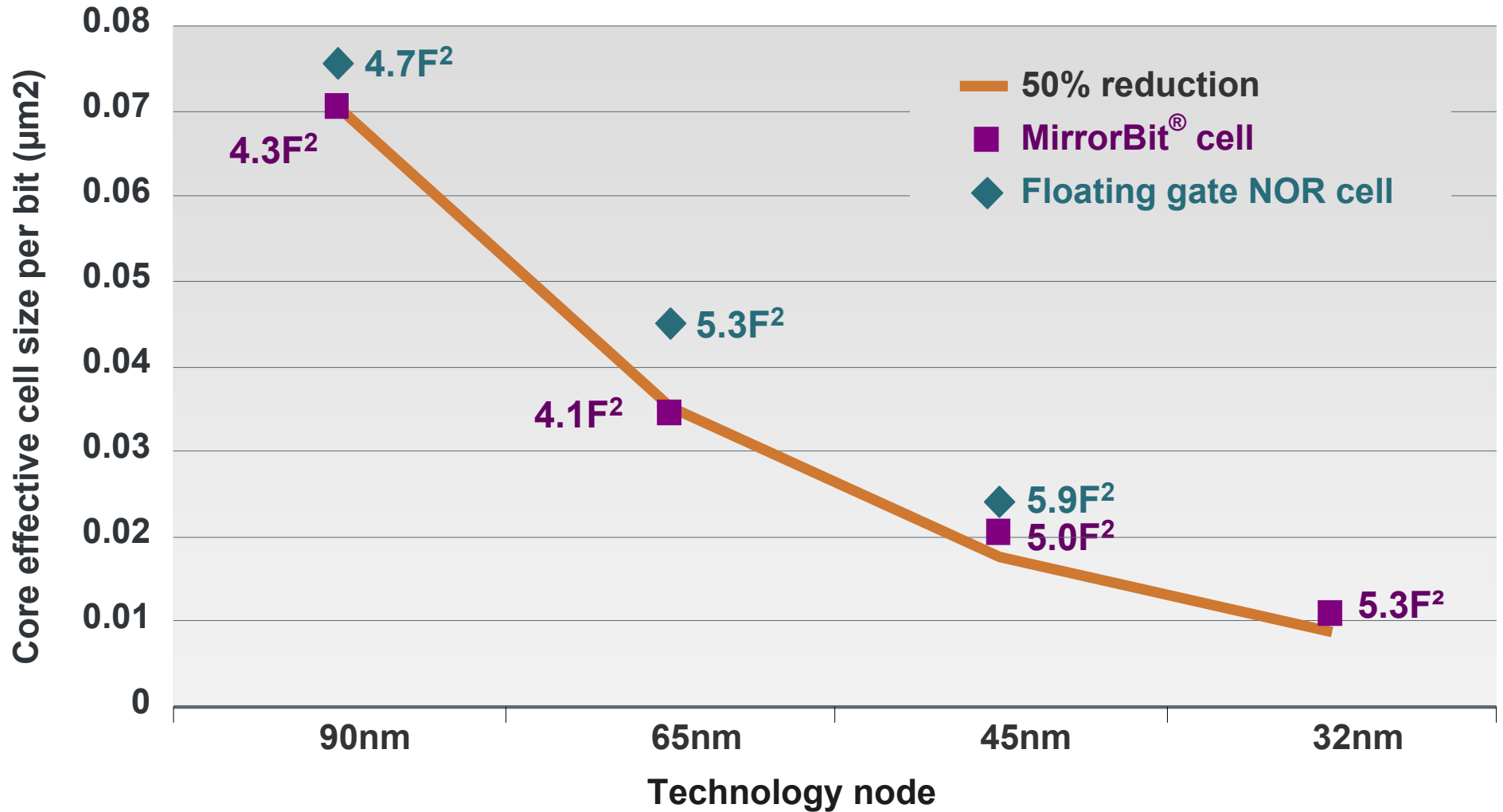
New technology must be “acceptable” for the customer



■ MirrorBit® technology share of NOR segment

Source: Spansion

# NOR Cell Size Scaling Example



Source: Spansion estimates

# What It Takes to Make “It” Work!



- Intimate Technology, Design, Product Eng, Test Collaboration
  - New & old technology aren’t the same – Different mindset required
  - **What works in the lab doesn’t necessarily work in production**
- Specific MirrorBit<sup>®</sup> technology design innovations

## *Advanced Program and Erase Algorithms*

- Temperature and cell location compensation
- Compact, uniform cell distributions
- Stabilizes cell behavior
- Optimizes data retention

## *Advanced Read*

- Increases margin by reducing parasitic currents
- Opens up sensing window

## *Advanced Process*

- Creating the highest technique in process

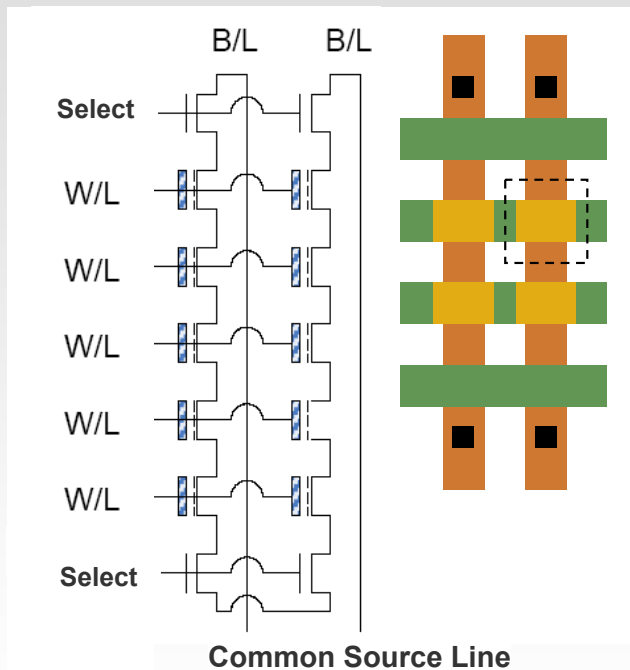


**Charge Trapping Next Steps  
with MirrorBit® NAND  
Technology  
“Evolution of Technology”**

# The Technology



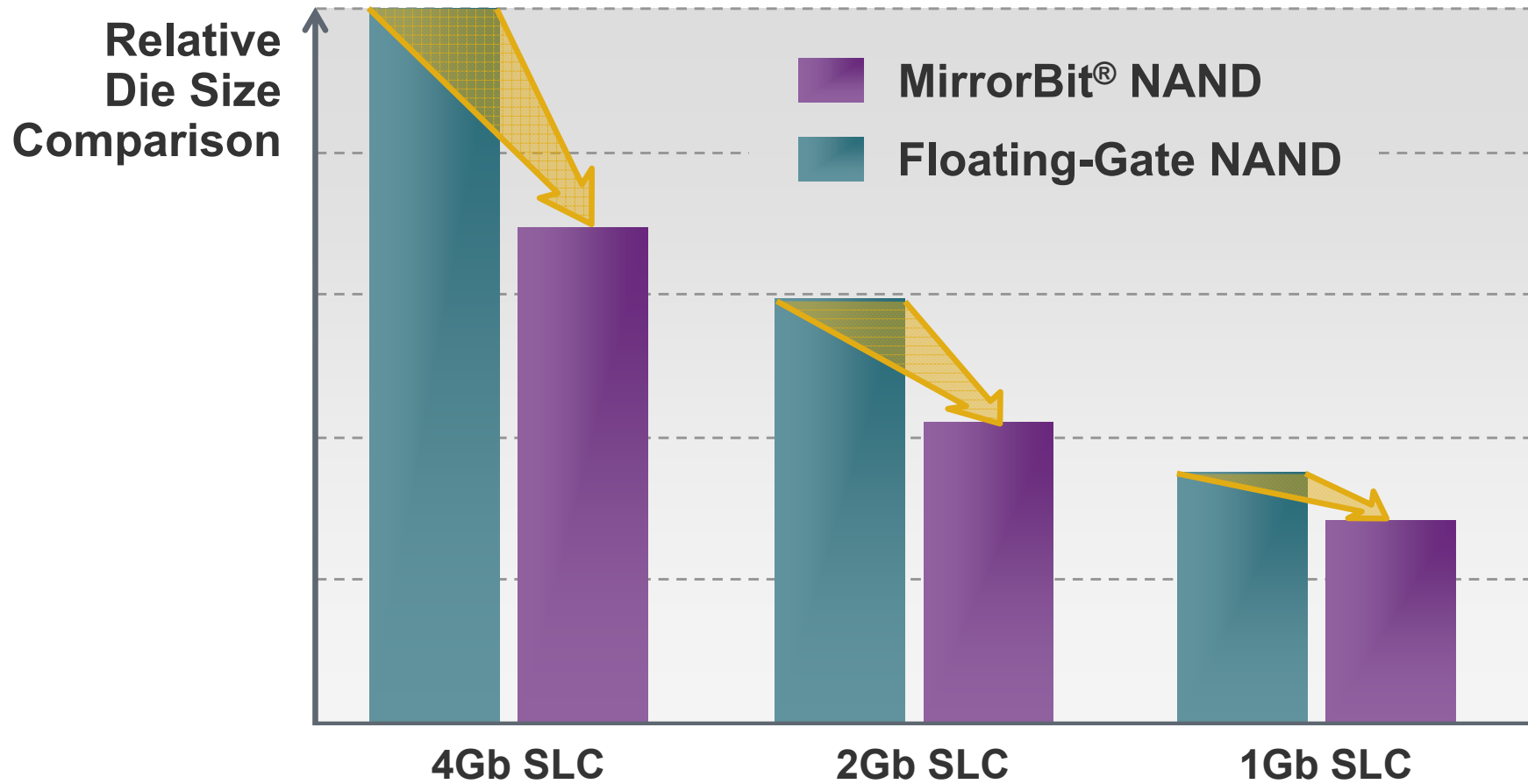
## MirrorBit® NAND Technology



Cell Size  $\sim 4.0\lambda^2$

- SONOS-like cell structure
- Cells connected in NAND array
- Highly scalable
- SLC and MLC capable
- Leverages proprietary MirrorBit® charge trapping technology and manufacturing know-how
- Different technology but excellent process compatibility with MirrorBit NOR for production in same fabs

# Efficient Die Size

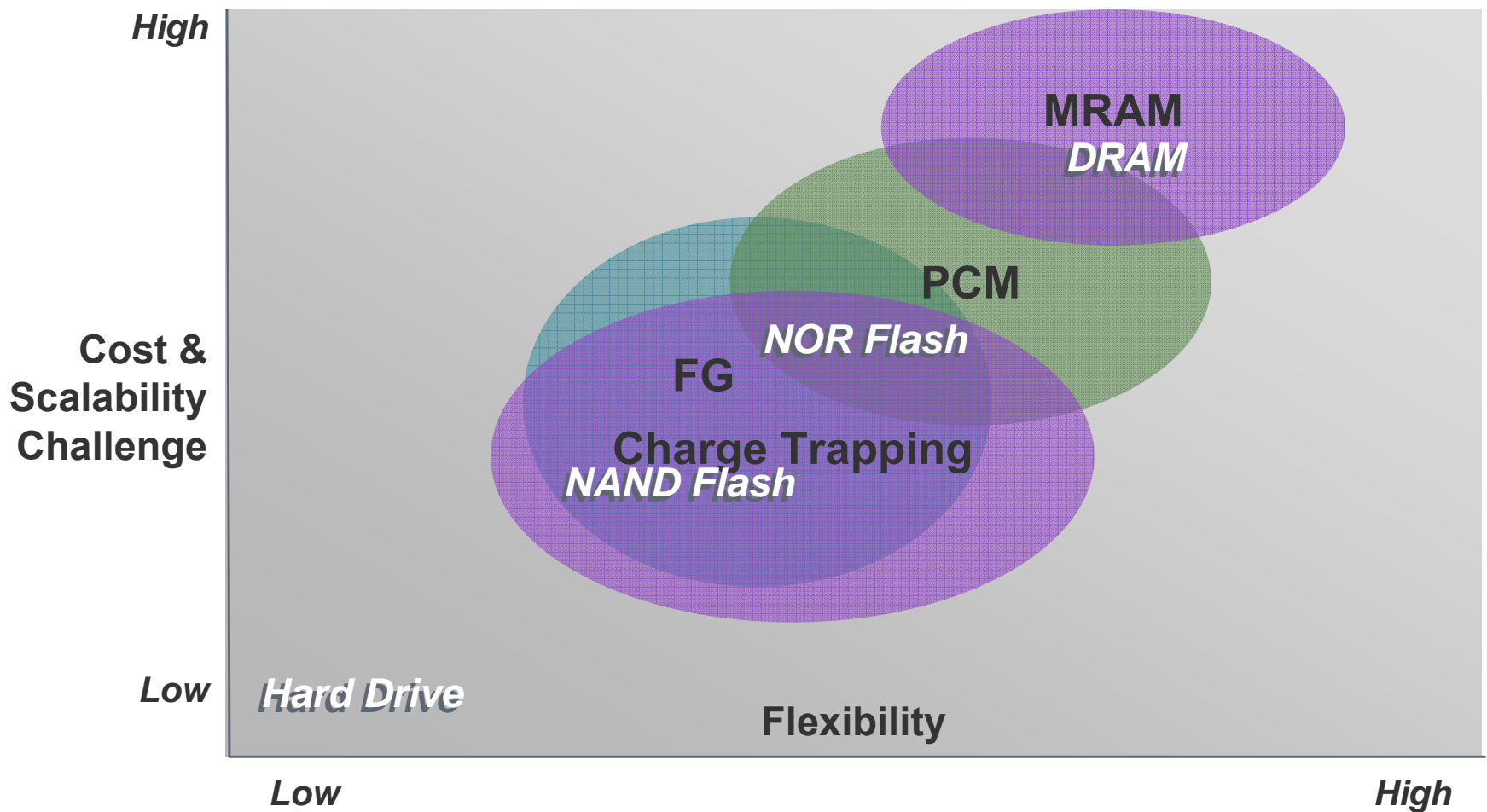


\* Source: Spansion estimates of MirrorBit<sup>®</sup> NAND versus 4xnm Floating gate SLC NAND solutions

# What Will the Future Look Like?



Moving closer to the ideal memory

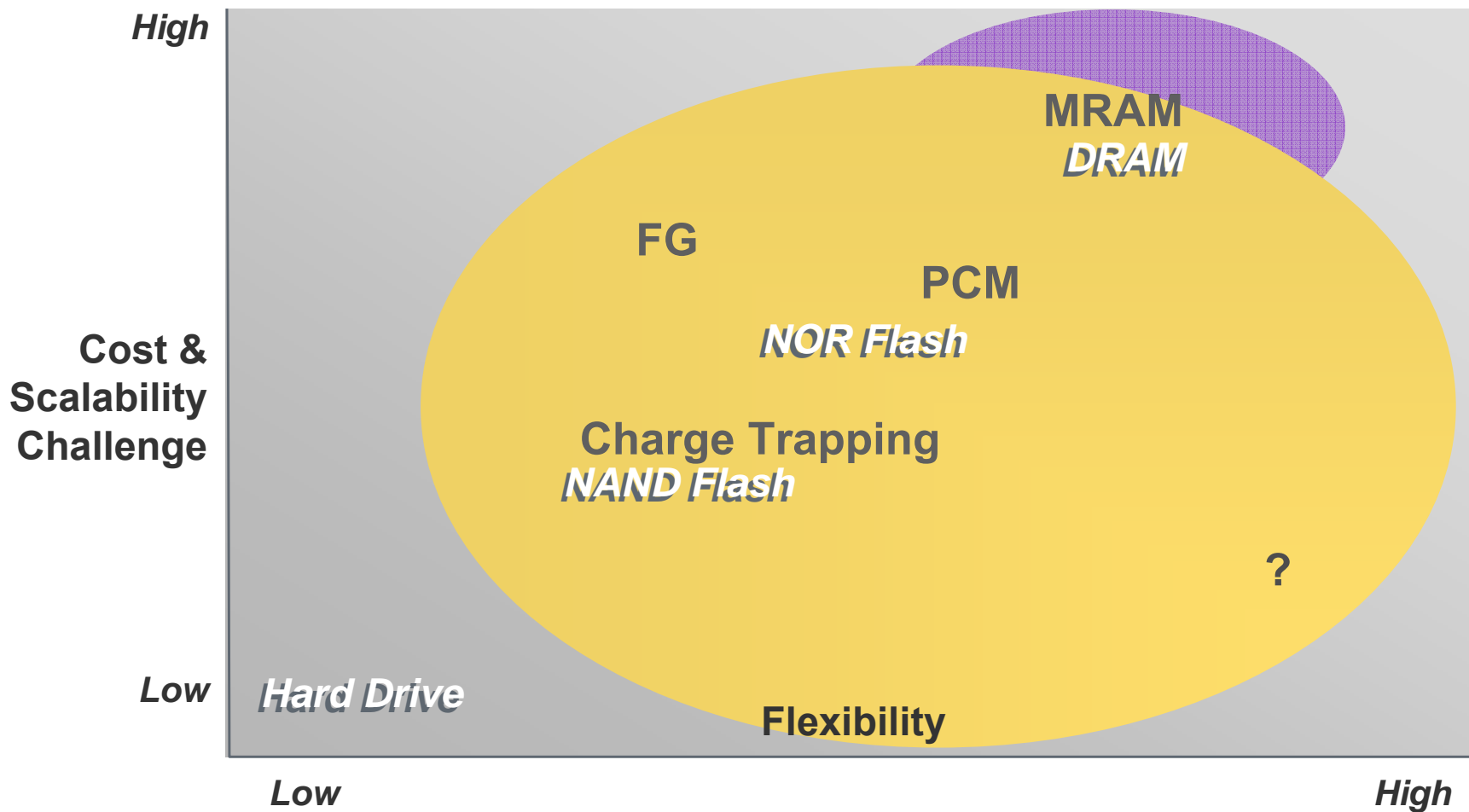


Source: Spansion

# What Will the Future Look Like?



Moving closer to the ideal memory



Source: Spansion

# Conclusion



## Existing industry is structured for evolution

- Even in Silicon Valley!
- Disruption can be risky – for both customers and suppliers
- It takes a long time to create new **Infrastructure** in a new Eco-System

## New technology is never adopted quickly

- Memory doesn't exist in a vacuum
- Even evolution takes a while
- Disruption needs H/W and S/W infrastructure to change

## Tomorrow's technologies...

- Must be relevant and must be viable
- Must offer more than today's technology ... otherwise why change?



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